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Planning for Hubs of Excellence Call Topic

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UCC
Coláiste na hOllscoile Corcaigh
University College Cork, Ireland

Rialtas na hÉireann
Government of Ireland

Tionscadal Éireann
Project Ireland 2040

Ireland's European Structural and Investment Funds Programmes 2014-2020
Co-funded by the Irish Government and the European Union

European Union
European Structural and Investment Funds

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Skills Workshop/matchmaking @EPoSS AF 2026

EPoSS.
European Association on Smart Systems Integration

Skills Workshop

Cian Ó Murchú

16/06/26

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Skills Hubs of Excellence
Topic: DIGITAL-JU-CHIPS-2026 -SKILLS-HoE-SG

Topic	Interests
Chip design and tools for chip design	3 RTOs, 2 Industry
Chip manufacturing, equipment metrology and testing	2 Industry, 1 RTO
Chiplets, heterogeneous integration, advanced packaging	3 Industry, 1 RTO
Technologies for photonic components and systems	3 RTOs, 2 Industry
Power electronics and wide bandgap materials	2 RTOs, 2 Industry

Countries: Ireland, Portugal, Spain, Austria

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Initial Ideas

- **European Joint Master's Programme** delivered through a consortium of multiple universities.
- **Industrial PhD Academy** to train doctoral candidates in close collaboration with industry.
- **Shared semiconductor training infrastructure and mobility scheme** enabling access to specialist facilities across partner institutions.
- **MSCA collaboration** to increase projects in semiconductor applications
- **European internship network with guaranteed placements** across academic and industrial partners.
- **International talent attraction programme** targeting selected countries.
- **Women in Semiconductors initiative** to improve female participation, retention, and progression.
- **Career orientation and awareness platform** promoting semiconductor career pathways and opportunities through roadshow, ambassadors, etc.
- **Integration with Chips Competence Centres and Pilot Lines** to ensure complementarity with existing EU capabilities.
- **Skills Observatory based on workforce intelligence data** to track evolving needs and guide programme design.
- **Micro-credential framework for reskilling and upskilling** aligned with industry needs.

EU Initiatives

Funding Agency	Initiative	Focus
CHIPS ACT 1.0 Chips for Europe	National Chips Competence Centres	Provide Semiconductor related training for Organizations
	Acccess CSA	Coordinating CCC Training Activities
	CHIPS JU Calls (CforE Initiative)	Three upcoming calls on Skills
	CHIPS JU Pilot Lines	Training Courses
DG CNECT	Industrial Alliance WG on Skills	Blueprint report & Video Promotion
Digital Europe	Projects such as RESCHIP4EU, Chips of Europe, Greenchips-edu	EU projects on Semiconductor training
ERASMUS+	European Chips Skills Academy, EU Chips Diversity Alliance, Centre of Vocational Excellence (upcoming)	Training and upskilling projects
IPCEI	IPCEI ME/CT - Important Project of Common European Interest	Training activities across all projects
EIT	28DGTL (formerly EIT Digital)	Masters Programmes, Online courses...
EU	Pact for Skills / Large Scale Partnership for the Microelectronics Ecosystem	Networking and collaboration

Other recent Initiatives:

- Digital Education Action Plan 2021-2027
- European Universities Initiative
- Harnessing Talent in Europe: a new boost for EU Regions
- European Digital Innovation Hubs
- EU STEM Coalition
- Research Infrastructures (INFRACHIP, RIANA)
- A STEM Education Strategic Plan: skills for competitiveness and innovation
- CSA projects such as ICOS^2 and JASMINE

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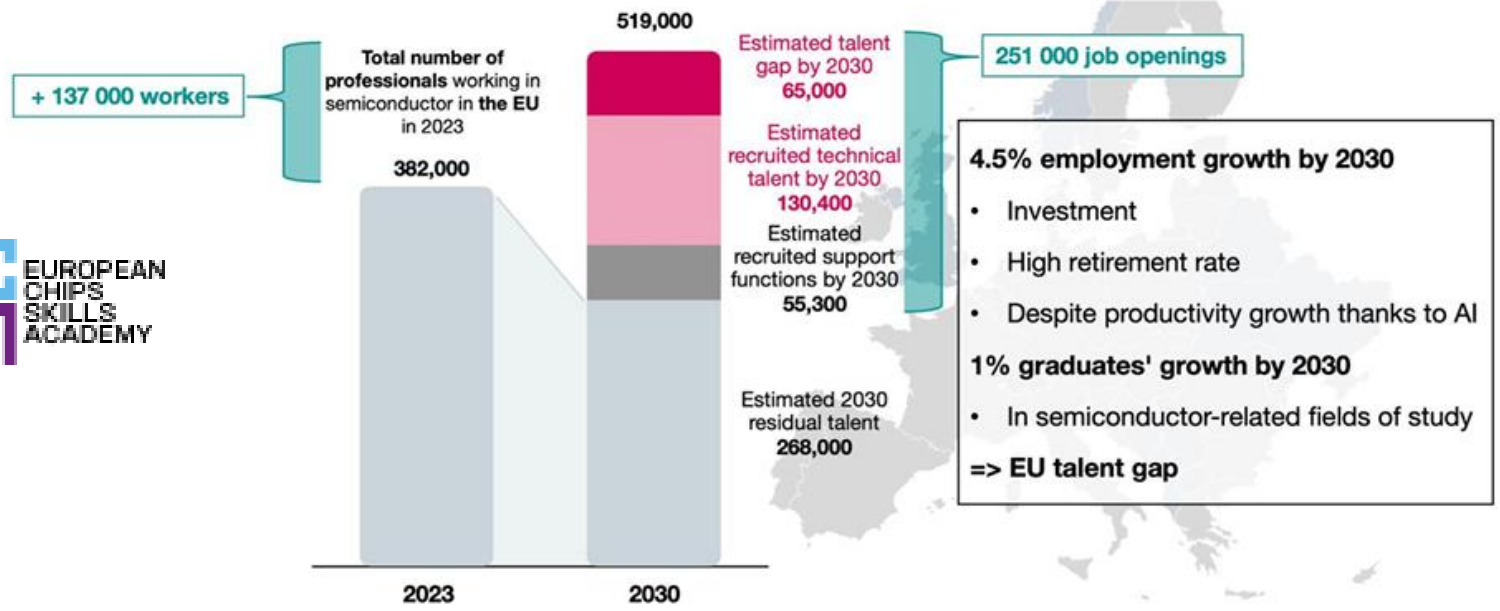
Skills Strategy Data

Figure 6: EU regions facing a talent gap versus talent surplus in semiconductor industry

EUROPEAN CHIPS SKILLS ACADEMY

Figure 5: EU Semiconductor Value Chain: Talent Gap Forecast (2024–2030)



Source: DECISION Etudes & Conseil, European Skills Strategy, ECSA, October 2025

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